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JOINT INDUSTRY STANDARD

Requirements for
Soldered Electrical
and Electronic
Assemblies

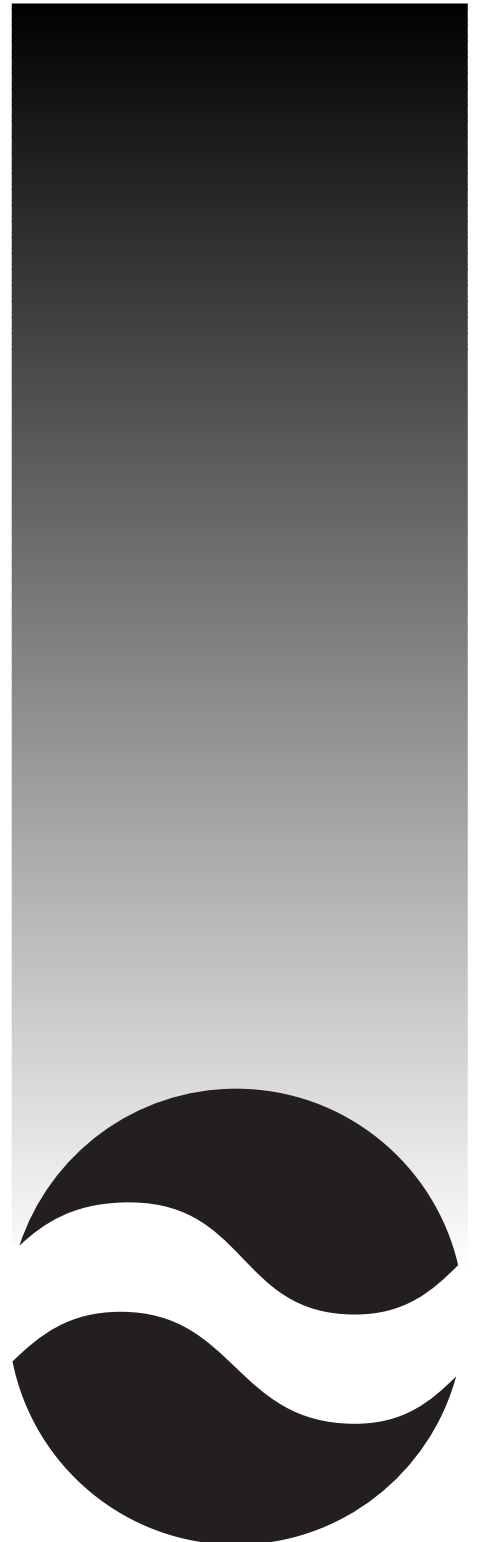


Table of Contents

1 SCOPE	1	4.2 Flux	5
1.1 Purpose	1	4.3 Solder Paste	5
1.2 Classification	1	4.4 Solder Preforms	5
1.3 Measurement Units and Applications	1	4.5 Adhesives	5
1.3.1 Verification of Dimensions	1	4.6 Chemical Strippers	5
1.4 Definition of Requirements	1	4.7 Heat Shrinkable Soldering Devices	5
1.4.1 Hardware Defects and Process Indicators	2	5 COMPONENTS	5
1.4.2 Material and Process Nonconformances	2	5.1 Solder Terminals	6
1.5 Process Control Requirements	2	5.2 Solderability	6
2 APPLICABLE DOCUMENTS	2	5.2.1 Solderability Testing of Ceramic Boards	6
2.1 Electronic Industries Alliance (EIA)	2	5.3 Solder Purity Maintenance	6
2.2 IPC	2	5.4 Solderability Maintenance	6
2.3 Joint Industry Standards	3	5.4.1 Gold Removal	6
2.4 ASTM	3	5.4.2 Rework of Nonsolderable Parts	6
2.5 Electrostatic Discharge Association	3	6 ASSEMBLY PROCESSES	7
3 GENERAL REQUIREMENTS	3	6.1 General Part Mounting Requirements	7
3.1 Order of Precedence	3	6.1.1 Component and Seal Damage	7
3.1.1 Conflict	3	6.1.2 Lead Forming	7
3.1.2 Specialized Processes and Technologies	3	6.1.2.1 Lead Deformation Limits	7
3.2 Terms and Definitions	3	6.1.2.2 Surface Mount Device Lead Forming	7
3.2.1 Defect	3	6.1.2.3 Flat Pack Parallelism	7
3.2.2 Disposition	4	6.1.2.4 Surface Mount Device Lead Bends	8
3.2.3 Manufacturer (Assembler)	4	6.1.2.5 Surface Mount Device Lead Deformation	8
3.2.4 Objective Evidence	4	6.1.2.6 Flattened Leads	8
3.2.5 Process Indicator	4	6.1.2.7 Dual-in-line Packages (DIPs)	8
3.2.6 Proficiency	4	6.1.3 Wire and Cable Preparation	8
3.2.7 Solder Destination Side	4	6.1.3.1 Tinning of Stranded Wire	8
3.2.8 Solder Source Side	4	6.1.4 Hole Obstruction	8
3.2.9 Supplier	4	6.1.5 Metal-Cased Component Isolation	8
3.2.10 User	4	6.1.6 Adhesive Coverage Limits	8
3.3 Requirements Flowdown	4	6.2 Bifurcated and Turret Terminal Installation	9
3.4 Personnel Proficiency	4	6.2.1 Shank Discontinuities	9
3.5 Electrostatic Discharge (ESD)	4	6.2.2 Flange Discontinuities	9
3.6 Facilities	4	6.2.3 Flared Flange Angles	9
3.6.1 Environmental Controls	4	6.2.4 Terminal Mounting - Mechanical	9
3.6.2 Temperature and Humidity	4	6.2.5 Terminal Mounting - Electrical	9
3.6.3 Lighting	4	6.3 Mounting to Terminals	10
3.6.4 Field Assembly Operations	4	6.3.1 General Requirements	10
3.6.5 Moisture Sensitive Components	5	6.3.1.1 Insulation Clearance (C)	10
3.7 Soldering Tools and Equipment	5	6.3.1.2 Service Loops	10
4 MATERIALS	5	6.3.1.3 Stress Relief	10
4.1 Solder	5	6.3.1.4 Orientation of Lead or Wire Wrap	11

6.3.1.5	Continuous Runs	11	7.3.2	Solder Bath	16
6.3.1.6	Insulation Sleeving (Wires Soldered to Pierced, Hook and Cup Terminals)	12	7.3.2.1	Solder Bath Maintenance	16
6.3.1.7	Lead and Wire End Extensions	12	7.4	Reflow Soldering	16
6.3.2	Bifurcated (Slotted) and Turret Terminals	12	8 CLEANLINESS REQUIREMENTS		16
6.3.2.1	Wire and Lead Wrap-Around - Turret and Straight Pin	12	8.1	Cleaning Process Requirements	16
6.3.2.1.1	Termination of Small Gauge Wire (AWG 30 and Smaller)	12	8.1.1	Pre-Soldering Cleanliness Requirements	16
6.3.2.2	Side Route Connection - Bifurcated Terminals	12	8.1.2	Post-Soldering Cleaning	17
6.3.2.3	Top and Bottom Route Connections	12	8.1.2.1	Ultrasonic Cleaning	17
6.3.3	Hook Terminals	12	8.2	Cleanliness Verification	17
6.3.4	Pierced or Perforated Terminals	12	8.2.1	Visual Inspection	17
6.3.5	Cup and Hollow Cylindrical Terminal Soldering	13	8.2.2	Testing	17
6.4	Surface Mounting of Components	14	8.3	Post-Solder Cleanliness	17
6.4.1	Parts Not Configured for Surface Mounting	14	8.3.1	Particulate Matter	17
6.4.2	Small Devices with Two Terminations	14	8.3.2	Flux Residues and Other Ionic or Organic Contaminants	17
6.4.2.1	Mounting of Parts on Parts (Stacking)	14	8.3.2.1	Post-Soldering Cleanliness Designator	17
6.4.2.2	Devices with External Deposited Elements ..	14	8.3.2.2	Visual Requirements	17
6.4.3	Leaded Component Body Positioning	14	8.3.3	Cleaning Option	17
6.4.3.1	Axial-Leaded Components	14	8.3.4	Test for Cleanliness	17
6.4.4	Parts Configured for Butt Lead Mounting	14	8.3.5	Rosin Flux Residues	18
6.5	Through-Hole Mounting	14	8.3.6	Ionic Residues (Instrument Method)	18
6.5.1	Lead Forming Requirements	14	8.3.7	Ionic Residues (Manual Method)	18
6.5.2	Lead Termination Requirements	14	8.3.8	Surface Insulation Resistance (SIR)	18
6.5.2.1	Lead Termination Requirements for Unsupported Holes	15	8.3.9	Other Contamination	18
6.5.3	Coating Meniscus	15	9 ASSEMBLY REQUIREMENTS		18
7 ASSEMBLY SOLDERING PROCESSES		15	9.1	Acceptance Requirements	18
7.1	General	15	9.1.1	Corrective Action Limits	18
7.1.1	Handling of Parts	15	9.1.2	Opportunities Determination	18
7.1.2	Preheating	15	9.2	General Assembly Requirements	18
7.1.3	Hold Down of Surface Mount Leads	15	9.2.1	Printed Wiring Assembly Damage	19
7.1.4	Cooling	15	9.2.1.1	Printed Wiring Board Damage	19
7.1.5	Lead Trimming	15	9.2.1.2	Component Damage	19
7.1.6	Solder Wicking	15	9.2.2	Markings	19
7.1.7	Drying/Degassing	15	9.2.3	Bow and Twist (Warpage)	19
7.1.8	Holding Devices and Materials	16	9.2.4	Solder Connection	19
7.2	Manual/Hand (Nonreflow) Soldering	16	9.2.4.1	Exposed Basis Metal	20
7.2.1	Flux Application	16	9.2.4.2	Solder Connection Defects	20
7.2.2	Solder Application	16	9.2.4.3	Partially Visible or Hidden Solder Connections	20
7.2.3	Heat Sinks	16	9.2.4.4	Soldering to Terminals	20
7.3	Machine (Nonreflow) Soldering	16	9.2.4.4.1	Bifurcated, Pierced or Perforated Terminals	20
7.3.1	Machine Controls	16	9.2.4.4.2	Cup Terminals	20
			9.2.5	Interfacial Connections	21
			9.2.5.1	Through-Hole Component Lead Soldering ...	21
			9.2.5.2	Through-Hole Lead Terminations	21

9.2.5.2.1 Straight Through Terminations 21

9.2.5.2.2 Clinched Leads 21

9.2.5.2.3 Coating Meniscus In Solder 22

9.2.6 Surface Soldering of Leads and Terminations 22

9.2.6.1 Misaligned Components 22

9.2.6.2 Unspecified Requirements 22

9.2.6.3 Special Class 1 SMT Requirements 22

9.2.6.4 Bottom Only Terminations 23

9.2.6.5 Rectangular or Square End Components 24

9.2.6.6 Cylindrical End Cap Terminations 25

9.2.6.7 Castellated Terminations 26

9.2.6.8 Flat, Ribbon, “L”, and Gull Wing Leads 27

9.2.6.9 Round or Flattened (Coined) Leads 28

9.2.6.10 “J” Leads 29

9.2.6.11 Butt Joints 30

9.2.6.12 Flat Lug Leads 31

9.2.6.13 Tall Profile Components Having Bottom Only Terminations 32

9.2.6.14 Inward Formed L-Shaped Ribbon Leads 33

9.2.6.15 Surface Mount Area Array Packages 34

9.2.7 Terminal Soldering 34

9.2.8 Connectors 34

10 COATING AND ENCAPSULATION 34

10.1 Conformal Coating 34

10.1.1 Application 34

10.1.1.1 Adjustable Components 34

10.1.1.2 Conformal Coating on Connectors 34

10.1.1.3 Conformal Coating on Brackets 34

10.1.2 Performance Requirements 34

10.1.2.1 Thickness 34

10.1.2.2 Coating Coverage 35

10.1.3 Rework of Conformal Coating 35

10.1.4 Conformal Coating Inspection 35

10.2 Encapsulation 35

10.2.1 Application 35

10.2.1.1 Encapsulant Free Surfaces 35

10.2.2 Performance Requirements 35

10.2.3 Rework of Encapsulant Material 35

10.2.4 Encapsulant Inspection 35

11 PRODUCT ASSURANCE 35

11.1 Hardware Defects Requiring Disposition 35

11.2 Inspection Methodology 39

11.2.1 Process Verification Inspection 39

11.2.2 Visual Inspection 39

11.2.2.1 Magnification Aids and Lighting 39

11.2.3 Sampling Inspection 39

11.3 Process Control 39

1.3.1 Defect and Process Indicator Reduction 39

12 REWORK AND REPAIR 40

12.1 Rework of Unsatisfactory Solder Connections 40

12.2 Repair 40

12.3 Post Rework/Repair Cleaning 40

13 MISCELLANEOUS REQUIREMENTS 40

13.1 Health and Safety 40

13.2 Special Manufacturing Requirements 40

13.2.1 Manufacture of Devices Incorporating Magnetic Windings 40

13.2.2 High Frequency Applications 40

13.2.3 High Voltage Applications 40

13.3 Guidance on Requirement Flowdown 40

Appendix A 41

Appendix B 43

Index 45

Figures

Figure 6-1 Surface Mount Device Lead Forming 7

Figure 6-2 Hole Obstruction 9

Figure 6-3 Flange Discontinuities 9

Figure 6-4 Flare Angles 9

Figure 6-5 Terminal Mounting - Mechanical 10

Figure 6-6 Terminal Mounting - Electrical 10

Figure 6-7 Insulation Clearance (C) Measurement 11

Figure 6-8 Service Loop for Lead Wiring 11

Figure 6-9 Stress Relief Examples 11

Figure 6-10 Continuous Runs 11

Figure 6-11 Wire and Lead Wrap Around 12

Figure 6-12 Side Route Connections and Wrap on Bifurcated Terminal 13

Figure 6-13 Top and Bottom Route Terminal Connection 13

Figure 6-14 Hook Terminal Connections 13

Figure 6-15 Pierced or Perforated Terminal Wire Wrap 13

Figure 6-16 Lead Bends 14

Figure 9-1 Solder Contact Angle (θ) 20

Figure 9-2 Acceptable Wetting of Plated-Through Holes without Leads 21

Figure 9-3 Through-Hole Component Lead Soldering - Minimum Acceptability for Classes 2 and 3 Per Table 9-1 21

Figure 9-4 Bottom Only Terminations 23

Figure 9-5 Rectangular or Square End Components 24

Figure 9-6 MELF Terminations 25

Figure 9-7 Castellated Terminations 26

Figure 9-8 Flat, Ribbon, “L,” and Gull Wing Leads 27

Figure 9-9 Round or Flattened (Coined) Leads 28

Figure 9-10 “J” Leads 29

Figure 9-11 Butt Joint 30

Figure 9-12 Flat Lug Leads 31

Figure 9-13 Tall Profile Components Having Bottom
Only Terminations 32

Figure 9-14 Inward Formed L-Shaped Ribbon Leads 33

Table 9-4 Dimensional Criteria - Bottom Only
Terminations 23

Table 9-5 Dimensional Criteria - Rectangular or
Square End Components 24

Table 9-6 Dimensional Criteria - MELF Terminations 25

Table 9-7 Dimensional Criteria - Castellated
Terminations 26

Table 9-8 Dimensional Criteria - Flat, Ribbon, “L,”
and Gull Wing Leads 27

Table 9-9 Dimensional Criteria - Round or Flattened
(Coined) Leads 28

Table 9-10 Dimensional Criteria - “J” Leads 29

Table 9-11 Dimensional Criteria - Butt Joints 30

Table 9-12 Dimensional Criteria - Flat Lug Leads 31

Table 9-13 Dimensional Criteria - Tall Profile
Components Having Bottom Only
Terminations 32

Table 9-14 Dimensional Criteria - Inward Formed
L-Shaped Ribbon Leads 33

Table 9-15 Terminal Soldering Requirements 34

Table 10-1 Coating Thickness 34

Table 11-1 Summary of Hardware Defects and Process
Indicators 36

Table 11-2 Magnification Aid Applications 39

Tables

Table 3-1 Design and Fabrication Specification 3

Table 5-1 Solder Limits for Tin/Lead Alloys 6

Table 6-1 Damaged Strand Limits 8

Table 6-2 Lead Bend Radius 14

Table 6-3 Lead Protrusion 15

Table 9-1 Plated-Through Holes with Component
Leads, Minimum Acceptable Conditions 21

Table 9-2 Lead Protrusion 22

Table 9-3 Surface Mount Components 22

Requirements for Soldered Electrical and Electronic Assemblies

1 SCOPE

This standard prescribes practices and requirements for the manufacture of soldered electrical and electronic assemblies. Historically, electronic assembly (soldering) standards contained a more comprehensive tutorial addressing principles and techniques. For a more complete understanding of this document's recommendations and requirements, one may use this document in conjunction with IPC-HDBK-001 and IPC-A-610.

When IPC/EIA J-STD-001 is cited or required by contract, the requirements of IPC-A-610 do not apply unless separately or specifically required. When IPC-A-610 is cited along with IPC/EIA J-STD-001, the order of precedence is to be defined in the procurement documents.

1.1 Purpose This standard describes materials, methods and acceptance criteria for producing soldered electrical and electronic assemblies. The intent of this document is to rely on process control methodology to ensure consistent quality levels during the manufacture of products. It is not the intent of this standard to exclude any procedure for component placement or for applying flux and solder used to make the electrical connection; however, the methods used **shall**¹ produce completed solder joints conforming to the acceptability requirements described in this standard.

The requirements for assembly, soldering, soldered connections, cleaning, coating/encapsulation, rework, and verification are defined in general terms.

(1) Requirement
See 1.4

1.2 Classification This standard recognizes that electrical and electronic assemblies are subject to classifications by intended end-item use. Three general end-product classes have been established to reflect differences in producibility, complexity, functional performance requirements, and verification (inspection/test) frequency. It should be recognized that there may be overlaps of equipment between classes.

The user (see 3.2.10) and manufacturer (see 3.2.3) **shall** agree on the class to which the product belongs. The product class should be stated in the procurement documentation package.

CLASS 1 General Electronic Products

Includes products suitable for applications where the major requirement is function of the completed assembly.

CLASS 2 Dedicated Service Electronic Products

Includes products where continued performance and extended life is required, and for which uninterrupted ser-

vice is desired but not critical. Typically the end-use environment would not cause failures.

CLASS 3 High Performance Electronic Products

Includes products where continued high performance or performance-on-demand is critical, equipment downtime cannot be tolerated, end-use environment may be uncommonly harsh, and the equipment must function when required, such as life support or other critical systems.

1.3 Measurement Units and Applications All dimensions and tolerances, as well as other forms of measurement (temperature, weight, etc.) in this standard are expressed in SI (System International) units (with Imperial English equivalent dimensions provided in brackets). Dimensions and tolerances use millimeters as the main form of dimensional expression; micrometers are used when the precision required makes millimeters too cumbersome. Celsius is used to express temperature. Weight is expressed in grams.

1.3.1 Verification of Dimensions Actual measurement of specific part mounting and solder fillet dimensions and determination of percentages are not required except for referee purposes. For the purposes of determining conformance to this specification, all specified limits in this standard are absolute limits as defined in ASTM E29.

1.4 Definition of Requirements The word **shall** is used throughout this document whenever a requirement is intended to express a provision that is binding.

Where the word **shall** leads to a hardware defect for at least one class, the requirements for each class are annotated in text boxes located adjacent to that occurrence in the text. These boxes are summarized in Table 11-1. Table 11-1 identifies each listed condition for each class as either "Defect," "Process Indicator," "Acceptable," or "No Requirement Specified." In case of a discrepancy between requirements in the text boxes and Table 11-1, requirements listed in the text boxes take precedence.

Line drawings and illustrations are depicted herein to assist in the interpretation of the written requirements of this standard. When tables or figures provide details of the requirements, the tables or figures take precedence over the text of this standard.

IPC-HDBK-001, a companion document to this specification, contains valuable explanatory and tutorial information compiled by IPC Technical Committees that is relative to this specification. Although the Handbook is not a part of

this specification, when there is confusion over the specification verbiage, the reader is referred to the Handbook for assistance.

Note: In previous revisions of this standard, the words “must” and “shall” had special meanings. In this revision (IPC/EIA J-STD-001C), the word “shall” has no special meaning beyond that commonly used in other IPC standards as stated above.

1.4.1 Hardware Defects and Process Indicators Hardware characteristics or conditions that do not conform to the requirements of this specification that are detectable by inspection or analysis are classified as either hardware defects or hardware process indicators. Hardware defects listed in the applicable text boxes **shall**¹ be identified and **shall**¹ be dispositioned, e.g., rework, scrap, use as is, repair. Not all process indicators specified by this standard are listed in the text boxes. Hardware process indicators should be monitored (see 11.3) but the hardware need not be dispositioned.

It is the responsibility of the user (see 3.2.10) to define unique defect categories applicable to the product. It is the responsibility of the manufacturer (see 3.2.3) to identify defects and process indicators that are unique to the assembly.

(1) Requirement
See 1.4

1.4.2 Material and Process Nonconformances Hardware found to be produced using either materials or processes that do not conform to the requirements of this standard **shall**² be dispositioned when the condition is a defect listed in the applicable text box. This disposition **shall**² address the potential effect of the nonconformance on functional capability of the hardware such as reliability and design life (longevity).

Note: Material and process nonconformances differ from hardware defects or hardware process indicators in that the material/process nonconformances often do not result in an obvious change in the hardware’s appearance but can impact the hardware’s performance; e.g., contaminated solder, incorrect solder alloy (per drawing/procedure).

(2) Table 11-1 #1a
Class 1-Defect
Class 2-Defect
Class 3-Defect

1.5 Process Control Requirements Process control methodologies **shall**³ be used (see 11.3) in the planning, implementation and evaluation of the manufacturing processes used to produce soldered electrical and electronic assemblies. The philosophy, implementation strategies, tools and techniques may be applied in different

(3) Requirement
See 1.4

sequences depending on the specific company, operation, or variable under consideration to relate process control and capability to end product requirements.

Class 3 **shall**⁴ develop and implement a documented process control system. This may or may not be a “statistical process control” system. The use of “statistical process control” (SPC) is optional and should be based on factors such as design stability, lot size, production quantities, and the needs of the company.

(4) Table 11-1 #1c
Class 1-No Req
Class 2-No Req
Class 3-Defect

2 APPLICABLE DOCUMENTS

The following documents, of the issue in effect on the date of invitation for bid, form a part of this specification to the extent specified herein.

2.1 Electronic Industries Alliance (EIA)¹

EIA-557-1 Statistical Process Control Guidance for the Selection of Critical Manufacturing Operations for Use in Implementing an SPC System for Passive Components

2.2 IPC²

IPC-HDBK-001 Requirements for Soldered Electrical and Electronic Assemblies Handbook

IPC-A-36 Cleaning Alternatives Board

IPC-T-50 Terms and Definitions for Interconnecting and Packaging Electronic Circuits

IPC-TR-467 Supporting Data and Numerical Examples for ANSI/J-STD-001B (Control of Fluxes)

IPC-A-610 Acceptability of Electronic Assemblies

IPC-OI-645 Standard for Visual Optical Inspection Aids

IPC-TM-650 Test Methods Manual

2.3.25 Detection and Measurement of Ionizable Surface Contaminants

2.3.27 Cleanliness Test Residual Rosin

2.3.28 Ionic Analysis of Circuit Boards Ion Chromatography Method

2.3.38 Surface Organic Contamination Detection Test

2.3.39 Surface Organic Contamination Identification Test (Infrared Analytical Method)

2.4.22 Bow and Twist

2.6.3 Moisture and Insulation Resistance, Rigid, Rigid/Flex and Flex Printed Wiring Boards

1. EIA, 2500 Wilson Blvd., Arlington, VA 22201-3834

2. IPC, 2215 Sanders Road, Northbrook, IL 60062

2.6.3.3 Moisture and Surface Insulation Resistance, Fluxes

IPC-SM-817 General Requirements for Dielectric Surface Mounting Adhesives

IPC-CC-830 Qualification and Performance of Electrical Insulating Compound for Printed Board Assemblies

IPC-2221 Generic Standard on PWB Design

IPC-2222 Sectional Standard on Rigid PWB Design

IPC-2223 Sectional Design Standard for Flexible Printed Boards

IPC-6011 Generic Performance Specification of Printed Boards

IPC-6012A Qualification and Performance Specification for Rigid Printed Boards

IPC-6013 Qualification and Performance for Flexible Printed Boards

IPC-9191 General Guidelines for Implementation of Statistical Process Control (SPC)

IPC-9201 Surface Insulation Resistance Handbook

2.3 Joint Industry Standards²

IPC/EIA J-STD-002 Solderability Tests for Component Leads, Terminations, Lugs, Terminals and Wires

J-STD-003 Solderability Tests for Printed Boards

J-STD-004 Requirements for Soldering Fluxes

J-STD-005 Requirements for Soldering Paste

J-STD-006 Requirements for Electronic Grade Solder Alloys and Fluxed and Non-Fluxed Solid Solders for Electronic Soldering Applications

IPC/JEDEC J-STD-020 Moisture/Reflow Sensitivity Classification for Plastic Integrated Circuit Surface Mount Devices

IPC/JEDEC J-STD-033 Standard for Handling, Packing, Shipping and Use of Moisture/Reflow Sensitive Surface Mount Devices

2.4 ASTM³

ASTM E29 Standard Practice for Using Significant Digits in Test Data to Determine Conformance with Specifications

2.5 Electrostatic Discharge Association⁴

ANSI/ESD-S-20.20 Protection of Electrical and Electronic Parts, Assemblies and Equipment

3 GENERAL REQUIREMENTS

The soldering operations, equipment, and conditions described in this document are based on electrical/electronic circuits designed and fabricated in accordance with the specifications listed in Table 3-1.

3.1 Order of Precedence The contract always takes precedence over this standard, referenced standards and drawings. In the event of a conflict between the text of this standard and the applicable documents cited herein, the text of this standard takes precedence.

Table 3-1 Design and Fabrication Specification

Board Type	Design Specification	Fabrication Specification
Generic Requirements	IPC-2221	IPC-6011
Rigid Printed Boards	IPC-2222	IPC-6012
Flexible Circuits	IPC-2223	IPC-6013
Rigid Flex Board	IPC-2223	IPC-6013

3.1.1 Conflict In the event of conflict between the requirements of this standard and the applicable assembly drawing(s)/documentation, the applicable user approved assembly drawing(s)/documentation **shall¹** govern. In the event of conflict between the requirements of this standard and an assembly drawing(s)/documentation that has not been approved, this standard **shall¹** govern.

(1) Requirement See I.4

When IPC/EIA J-STD-001 is cited or required by contract, the requirements of IPC-A-610 do not apply unless separately or specifically required. When IPC-A-610 or other related documents are cited along with IPC/EIA J-STD-001, the order of precedence is to be defined in the procurement documents.

3.1.2 Specialized Processes and Technologies Mounting and soldering requirements for specialized processes and/or technologies not specified herein **shall²** be performed in accordance with documented procedures which are available for review.

(2) Requirement See I.4

3.2 Terms and Definitions Other than those terms listed below, the definitions of terms used in this standard are in accordance with IPC-T-50.

3.2.1 Defect A nonconformance to the requirements of this standard (listed in or referenced by Table 11-1) or other risk factors as identified by the manufacturer. A process and/or material nonconformance that could result in a reduction of functional capability, design life or reliability.

3. ASTM, 100 Barr Harbor Drive, West Conshohocken, PA 19428

4. ESD Association, 7900 Turin Road, Bldg. 3, Ste. 2, Rome, NY 13440